

INFORMATION DISCLOSURE CITATION
(37 CFR 1.97)

Application Number
Filing Date
First Named Inventor Rutten
Group Art Unit
Examiner Name
Attorney Docket US 018179

Jc955 U.S. PTO
10/005974
11/08/01

#2

U.S. PATENT DOCUMENTS

Examiner's Initials	Cite No.	Patent Number	Date	Name	Class	Sub-Class	Filing Date, If Approp.
	AA	6,075,373	13 June 2000	Iino			
EP	AB	6,169,410 B1	2 January 2001	Grace et al.			
EP	AC	(copending application) "CHIP-MOUNTED CONTACT SPRINGS"	10/05, 689 11/08/01	Rutten			(concurrent)
	AD						
	AE						
	AF						
	AG						
	AH						

FOREIGN PATENT DOCUMENTS

Examiner's Initials	Cite No.	Patent Number	Date	Country	Class	Sub-Class	Translation	
							Yes	No
EP	AI	EP 0 755 071 A2	18 July 1996	Europe				
	AJ							
	AK							
	AL							
	AM							

Examiner's Initials	Cite No.	Other (Include Author, Title, Date, Pertinent Pages, Etc.)
EP	AN	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg2.html
EP	AO	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg5.html
EP	AP	"Focus on FormFactor", THE FINAL TEST REPORT, Vol. 12, No. 09, September 2001, Ikonix Corp. P.O. Box 1938, Lafayette, CA 94549-1938
EP	AQ	"Flip-Chip Bonding on 6-um Pitch using Thin-Film Microspring Technology", Donald L. Smith et al., Xerox Palo Alto Research Center, Proceedings, 48 th Electronic Components and Technology Conference, IEEE, May 1998.
	AR	

Examiner	Evan Pert	Date Considered	6/5/03
Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include a copy of this form with next communication to the Applicant.			